

# ABSTRACT OF THE DISCLOSURE

In mounting of electronic component for mounting a connection terminal (5a) of an electronic component (5) by bonding to electrodes (2) of a substrate (1) by using solder paste (4) mixing solder particles in thermosetting adhesive, the solder  
5 paste (4) is supplied to the electrodes (2) and recess (3) as adhesion reinforcing portion provided in other portion, and solder print parts (4A, 4B) are formed, and the electronic component (5) is mounted, and the connection terminal (5a) and main body (5b) of electronic component (5) are adhered to the solder print parts (4A, 4B), and are heated in this state by reflow. As a result, the connection terminal (5a) and  
10 electrodes (2) are bonded by solder junction (6a), and by the adhesive component of the solder print part (4B), second resin reinforced part (7b) is formed for fixing the main body (5b) and substrate (1).